

Title (en)

LED CHIP AND METHOD FOR MANUFACTURING THE SAME

Title (de)

LED-CHIP UND HERSTELLUNGSVERFAHREN DAFÜR

Title (fr)

PUCE DE DIODE ÉLECTROLUMINESCENTE ET SON PROCÉDÉ DE FABRICATION

Publication

**EP 2759001 A4 20150429 (EN)**

Application

**EP 12833315 A 20120822**

Priority

- CN 201110282701 A 20110922
- CN 2012080472 W 20120822

Abstract (en)

[origin: WO2013040974A1] An LED chip and a method for manufacturing the same are provided. The method comprises steps of: a) providing an epitaxial wafer including a substrate, and a buffer layer, an n-type semiconductor layer, a light-emitting layer and a p-type semiconductor layer formed on the substrate sequentially; b) forming a conductive layer on the epitaxial wafer, and etching the conductive layer to form a plurality of first grooves in the conductive layer; c) providing a mold having a plurality of protrusions corresponding to the plurality of first grooves, and forming a phosphor layer on a surface of the mold having the plurality of protrusions; d) pressing the mold on the conductive layer vertically, so as to insert the plurality of protrusions into the corresponding first grooves; and e) performing a heat treatment, and removing the mold.

IPC 8 full level

**H01L 33/50** (2010.01); **H01L 33/20** (2010.01); **H01L 33/38** (2010.01)

CPC (source: EP)

**H01L 33/20** (2013.01); **H01L 33/505** (2013.01); **H01L 33/38** (2013.01); **H01L 2933/0041** (2013.01)

Citation (search report)

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- [IA] US 2010181591 A1 20100722 - SUZUKI FUMIO [JP]
- [A] US 2010291313 A1 20101118 - LING PEICHING [US]
- [A] KR 101011757 B1 20110207 - LG INNOTEK CO LTD [KR] & EP 2375457 A2 20111012 - LG INNOTEK CO LTD [KR]
- See references of WO 2013040974A1

Designated contracting state (EPC)

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